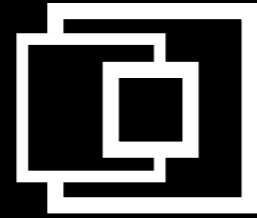


# Osai Automation Systems



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Automatic Line Example

**Modular • Configurable • Scalable • Reusable**

**SOLUTIONS FOR POWER DEVICES PRODUCTION**

**PICK & PLACE**



This equipment is used to assemble different parts of power modules such as: dice, lead frame, preform and plastic case.

**KEYPOINTS**

**Suitable for:**  
Dice, Preform, AMB, Lead Frame, Plastic Case

**Configurable Input Media**  
Tray, Blister, Tape & Reel, Bulk, Film Frame

**High Accuracy**  
±5µm

**High Speed**  
Up to 1sec/cycle



**PIN INSERTION**



This equipment is used to place the pins on the substrate. It works for both wired (inserted) and coil pins (punched and soldered in the next phase).

**KEYPOINTS**

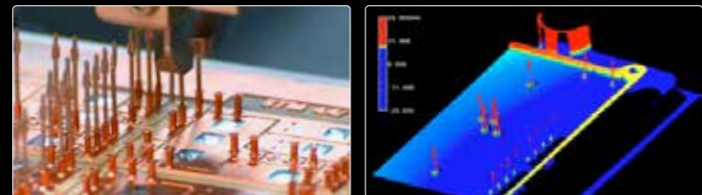
**Suitable for:**  
Wired Pins and Coil Pins

**High Accuracy**  
±5µm

**Pin Insertion Check**  
Height ±50µm  
Force Control Up to 500N

**High Speed**  
Up to 2pins/s

**Optical Features**  
Single Pin Optical Alignment  
3D Scan Check



**DISPENSING / VACUUM POTTING**



This equipment can be configured with: glue, flux jet dispenser (with integrated optical check and UV curing) or SilGel dispenser (two components volumetric dispenser) with vacuum potting chamber.

**KEYPOINTS**

**Suitable for:**  
Ultra Fast Jet Dispensing / Two Components Volumetric Dispensing

**Design for:**  
Flux, Glue and SilGel

**High Accuracy**  
±5µm

**Optical Features**  
UV Lighting Vision System  
Long Life LED UV Curing

**High Speed**  
Up to 300PH

**Additional Features**  
Vacuum Potting Chamber  
Weight Check



**SOLDERING / WELDING**



According to the connection method, the equipment can be configured to perform Vacuum induction soldering or ultrasonic welding.

**KEYPOINTS**

**Suitable for:**  
Lead Frame Welding / Pin Soldering

**High Accuracy**  
±5µm

**Top notch technology**  
Linear or Torsional Ultrasonic Welding  
Patented Vacuum Induction Soldering

**Optical Features**  
Full Optical Alignment  
Quality Optical Inspection



**LASER MARKING**



The equipment is used to mark every single leadframe / AMB and device, to allow each single unit traceability. The green Laser source is the ultimate solution for a fast and accurate marking on copper, silver, ceramic substrate and plastic case.

**KEYPOINTS**

**LASER**  
Green

**Fiducial check**  
For accurate marking position

**100% data and grading check**  
On 1D/2D code

**Optical check**  
For component presence/absence

**Full library**  
(2D code, Bar code, QR code and others)

**Tailored DB communication**  
For traceability

